

SMD ■ B EASV2713RGBA3



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Multi-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Descriptions

- The EASV2713 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Red	
InGaN	Brilliant Green	White Clear
InGaN	Blue	

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	R6:25 GH:25 BH:25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	R6:60 GH:100 BH:100	mA
Power Dissipation	P_d	R6:60 GH:95 BH:95	mW
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +90	°C
Electrostatic Discharge(HBM)	ESD_{HBM}	R6:2000 GH:150 BH:150	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition	
Luminous Intensity	Iv	R6	45.0	-----	112	mcd	
		GH	28.5	-----	112		
		BH	11.5	-----	28.5		
Viewing Angle	2θ _{1/2}	-----	120	-----	deg		
Peak Wavelength	λ _p	R6	-----	632	-----	nm	
		GH	-----	518	-----		
		BH	-----	468	-----		
Dominant Wavelength	λ _d	R6	-----	624	-----	nm	I _F =5mA
		GH	520	-----	535		
		BH	465	-----	475		
Spectrum Radiation Bandwidth	Δλ	R6	-----	20	-----	nm	
		GH	-----	35	-----		
		BH	-----	25	-----		
Forward Voltage	V _F	R6	1.9	2.05	2.3	V	
		GH	2.6	2.9	3.2		
		BH	2.6	2.9	3.2		
Reverse Current	I _R	R6	-----	-----	10	μA	V _R =5V
		GH	-----	-----	50		
		BH	-----	-----	50		

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.10V

R6

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
P	45.0	72.0	mcd	I _F =5mA
Q	72.0	112		

GH

Bin Range of Luminous Intensity

Bin Code.	Min.	Max.	Unit	Condition
N	28.5	45.0	mcd	I _F =5mA
P	45.0	72.0		
Q	72.0	112.0		

Bin Range Of Dom. Wavelength

Bin Code.	Min.	Max.	Unit	Condition
1	520	525	nm	I _F =5mA
2	525	530		
3	530	535		

BH

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
L	11.5	18.0	mcd	I _F =5mA
M	18.0	28.5		

Bin Range Of Dom. Wavelength

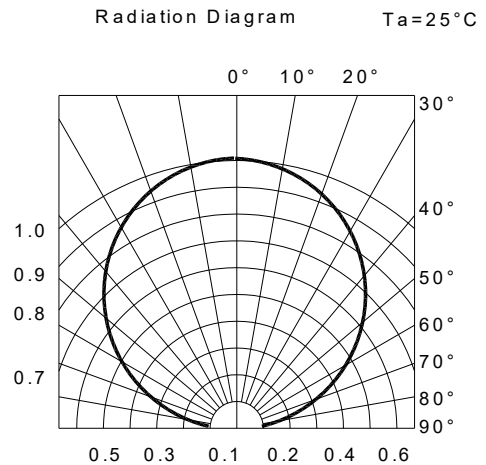
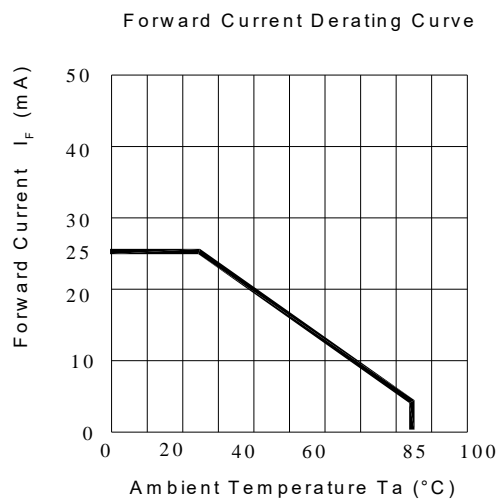
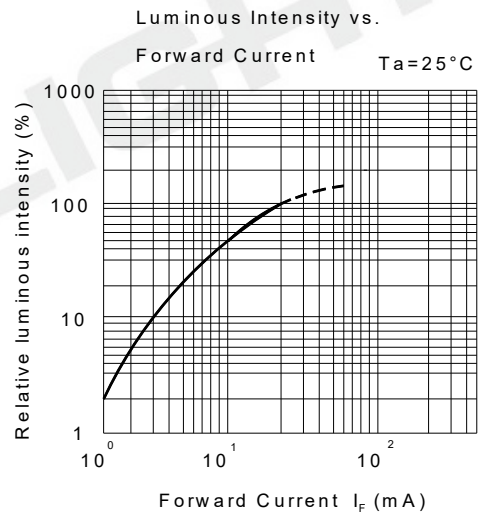
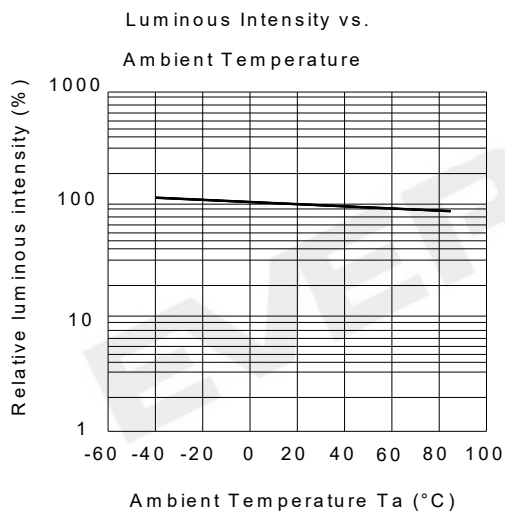
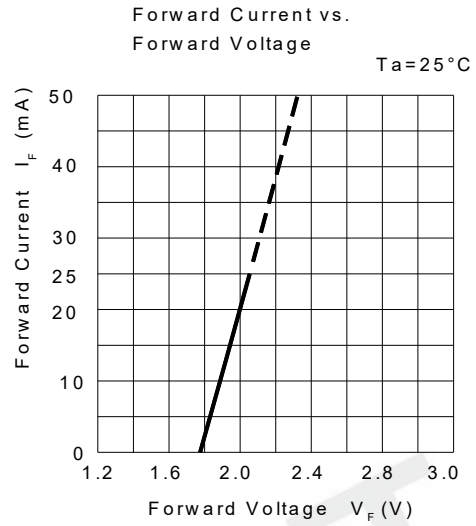
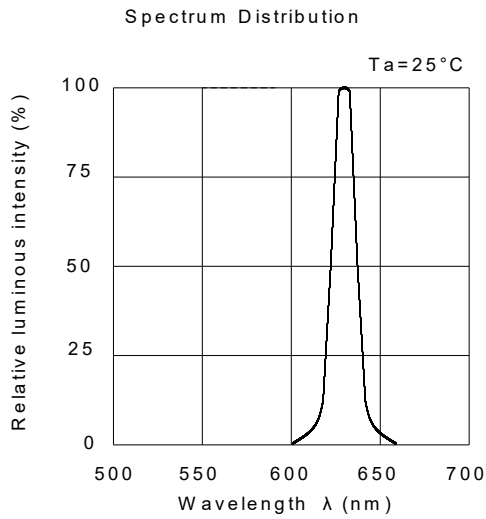
Bin Code.	Min.	Max.	Unit	Condition
1	465	470	nm	I _F =5mA
2	470	475		

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm

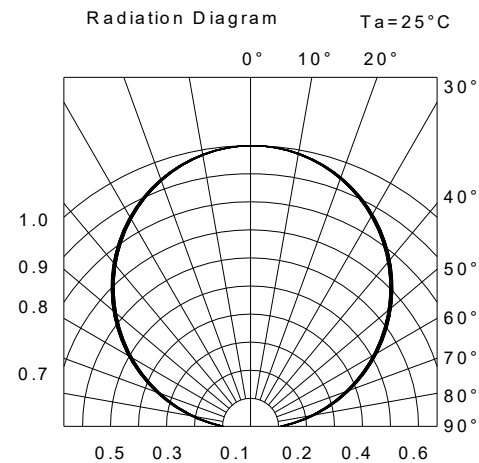
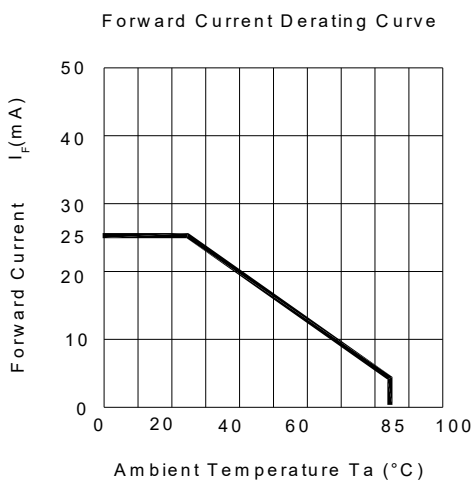
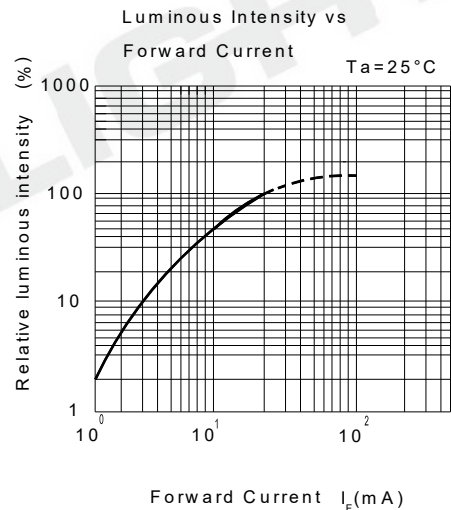
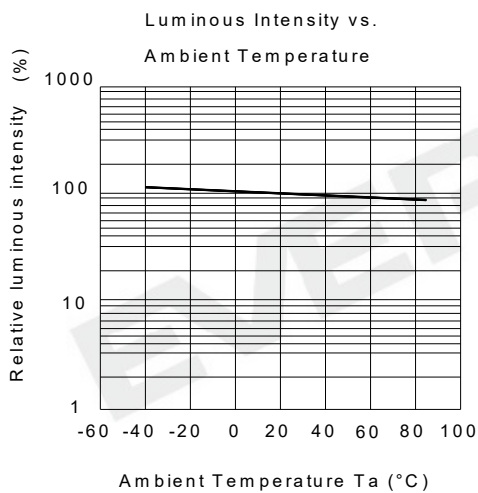
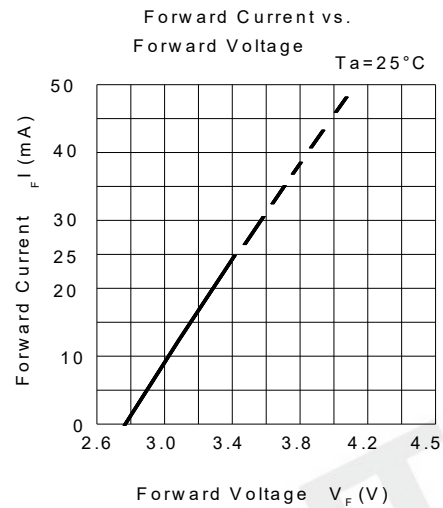
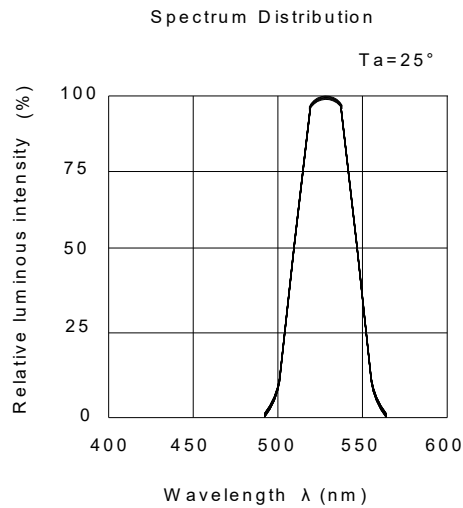
Typical Electro-Optical Characteristics Curves

R6



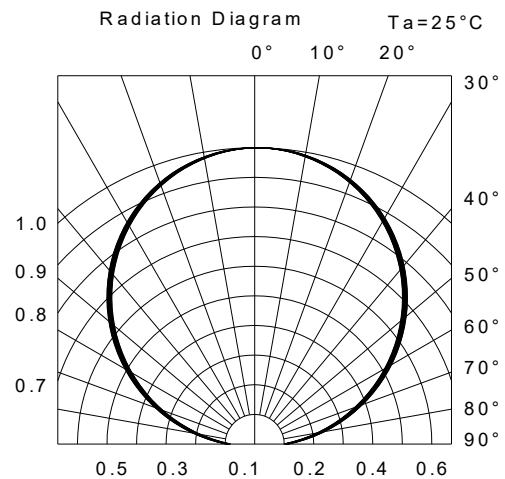
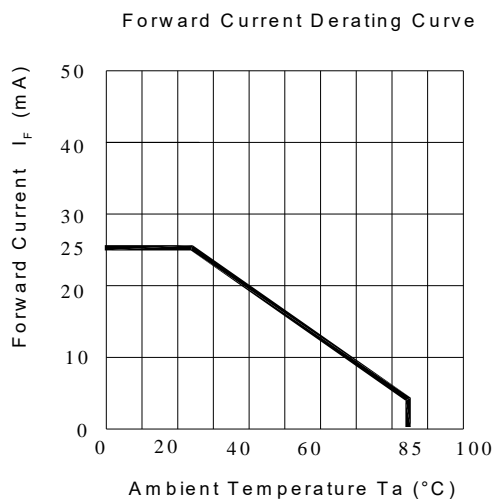
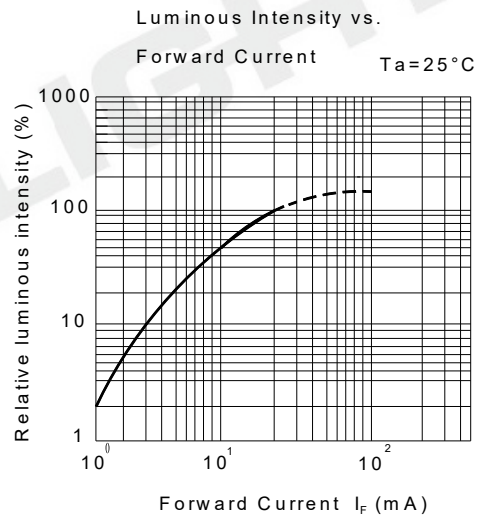
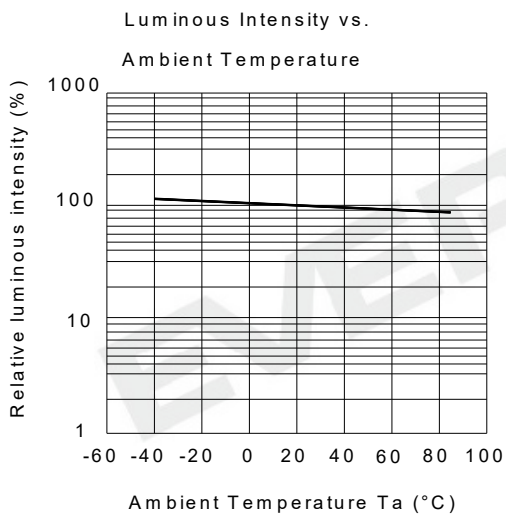
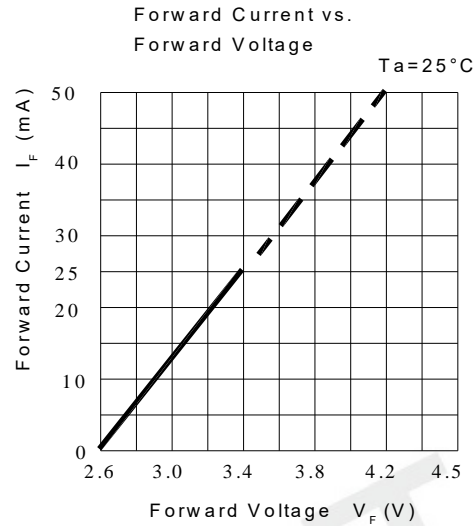
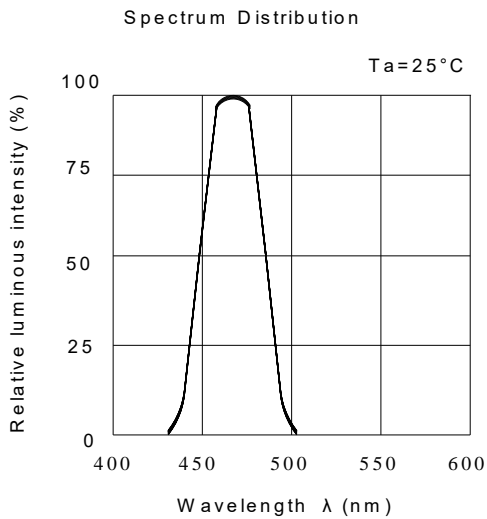
Typical Electro-Optical Characteristics Curves

GH

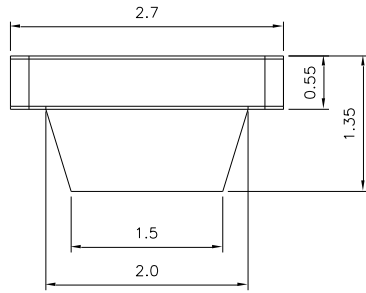
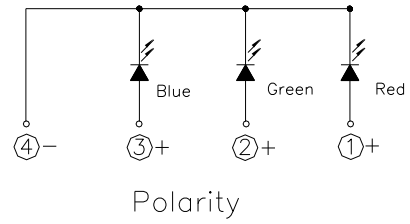
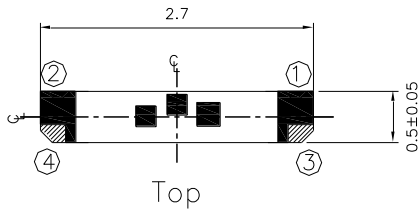


Typical Electro-Optical Characteristics Curves

BH

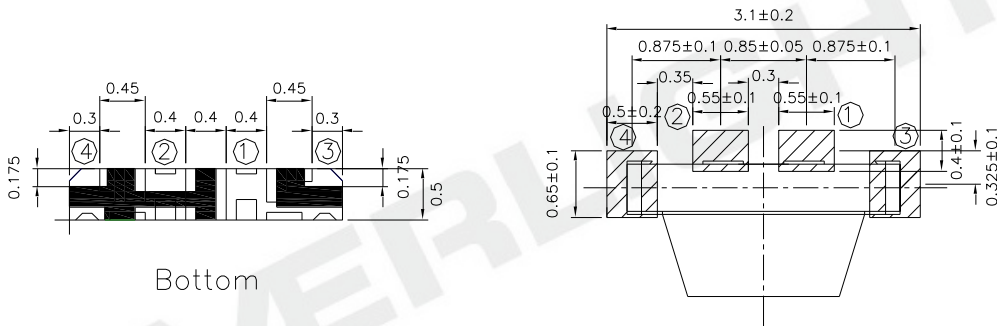


Package Outline Dimensions



Top view

Recommend Soldering Pad



Bottom

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm

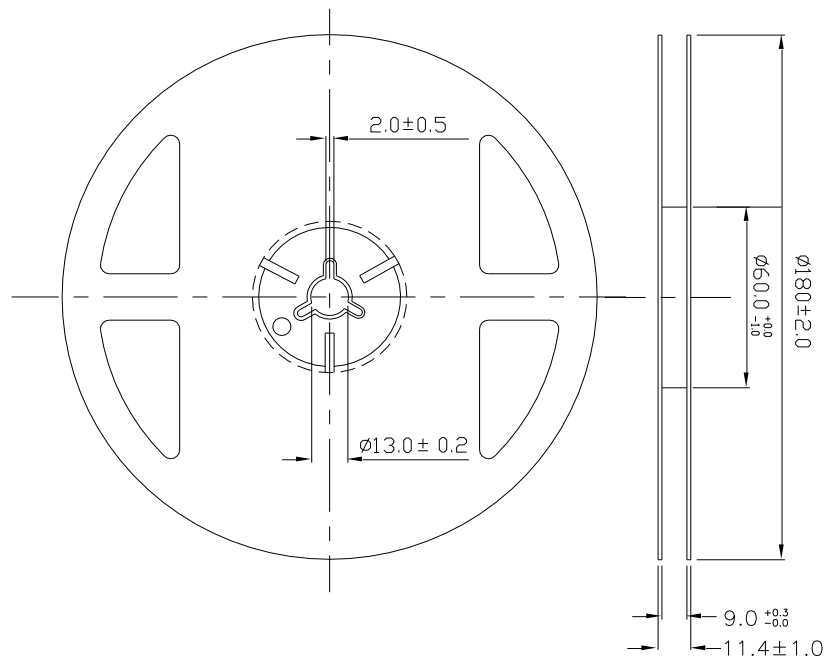
Moisture Resistant Packing Materials

Label Explanation



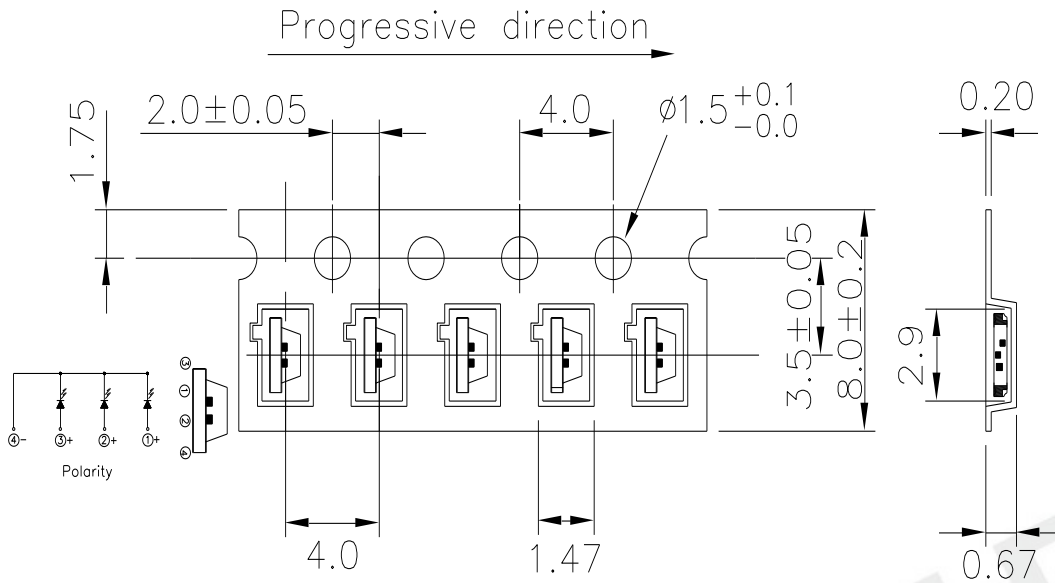
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions



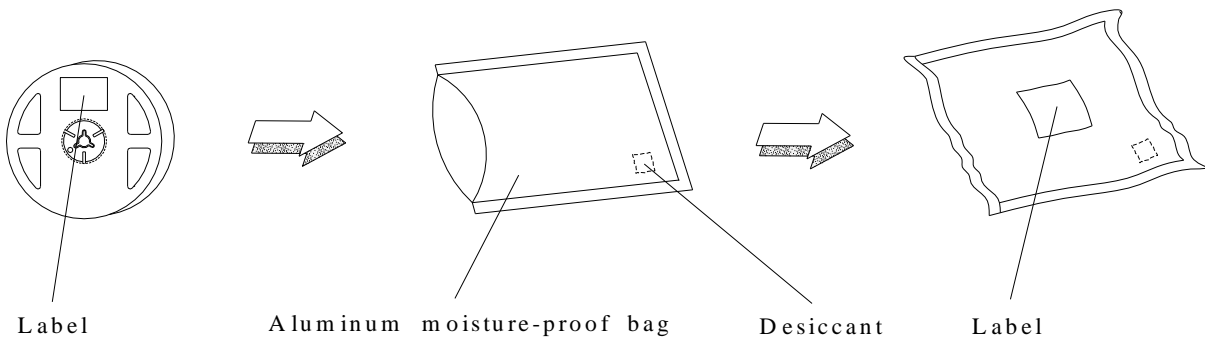
Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Moisture Resistant Packing Process



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Precautions for Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less.

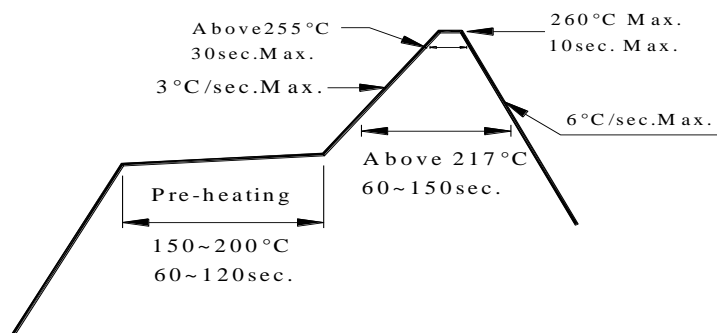
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : (

3. Soldering Condition

3.1 Pb-free solder t



3.2 Reflow profile, frequency are based on IPC/JEDEC J-STD-20D.

3.3 When soldering, do not put stress on the LEDs during heating.

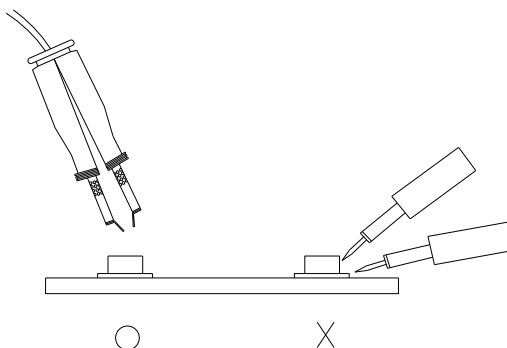
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

EVERLIGHT